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11-21-03

To the Honorable Commissioner of Patents and Trademarks. Please record the attached original documents or copy thereof.

1. Name of conveying party(ies):

Toshifumi MATSUSHIMA, Hildeaki MIWA, Akira ICHIRYU,

Kazuhiro YAMZAKI, Tetsuro SATO, Fujio KUWAKO

Additional name(s) of conveying
party(ies) attached? ☐ Yes ☒ No

2. Name and address of receiving party(ies):

NAME: Mitsui Mining & Smelting Co., Ltd.

ADDRESS: 11-1, Osaki 1-chome, Shinagawa-ku
Tokyo 141-8584, JapanAdditional name(s) & addresses(es) attached?
☐ Yes ☒ No

3. Name of Conveyance:

☒ Assignment ☐ Merger☐ Security Agreement ☐ Change of Name☐ Other

Execution/Effective Date: September 8, 2003

10/478419

4. Application number(s) or patent number(s):

If this document is being filed together with a new application, the execution date of the application is: September 8, 2003

A. Patent Application No.(s)

PCT/JP03/04172

B. Patent No.(s)

Additional numbers attached? ☐ Yes ☒ No5. Name and address of party to whom correspondence
concerning document should be mailed:Name: Robert B. Murray
Internal Address: Rothwell, Figg, Ernst & Manbeck
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Attorney Docket No.: 2922-465

6. Total number of applications
and patents involved: 17. Total fee (37 CFR 3.41): . . . \$ 40☒ Enclosed☐ Authorized to be charged to deposit account

8. Deposit account number: 02-2135

Attach duplicate copy of this page if paying by
deposit account

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9. Statement and signature.

*To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a
true copy of the original document.*Robert B. Murray
Name of Person Signing

Signature

Date

Total number of pages including cover sheet, attachments and documents: 2

ASSIGNMENT OF PATENT APPLICATION

WHEREAS, I/We Toshifumi MATSUSHIMA, a citizen of JAPAN, residing at c/o Mitsui Mining & Smelting Co., Ltd. Corporate R&D Center, 1333-2, Haraichi, Ageo-shi, Saitama 362-0021, Japan, Hideaki MIWA, a citizen of JAPAN, residing at c/o Mitsui Mining & Smelting Co., Ltd. Corporate R&D Center, 1333-2, Haraichi, Ageo-shi, Saitama 362-0021, Japan, Akira ICHIRYU, a citizen of JAPAN, residing at c/o Mitsui Mining & Smelting Co., Ltd. Corporate R&D Center, 1333-2, Haraichi, Ageo-shi, Saitama 362-0021, Japan, Kazuhiro YAMAZAKI, a citizen of JAPAN, residing at c/o Mitsui Mining & Smelting Co., Ltd. Copper Foil Sector Copper Foil Division, 656-2 Kamakurabashi, Ageo-shi, Saitama 362-0013, Japan, Tetsuro SATO, a citizen of JAPAN, residing at c/o Mitsui Mining & Smelting Co., Ltd. Copper Foil Sector Copper Foil Division, 656-2 Kamakurabashi, Ageo-shi, Saitama 362-0013, Japan, and Fujio KUWAKO, a citizen of JAPAN, residing at c/o Mitsui Mining & Smelting Co., Ltd. Copper Foil Sector Copper Foil Division, 656-2 Kamakurabashi, Ageo-shi, Saitama 362-0013, Japan

ASSIGNOR(S), am/are the inventor(s) of an invention in DIELECTRIC FILLER CONTAINING RESIN FOR USE IN FORMATION OF BUILT-IN CAPACITOR LAYER OF PRINTED WIRING BOARD AND DOUBLE-SIDED COPPER CLAD LAMINATE WITH DIELECTRIC LAYER FORMED USING THE SAME DIELECTRIC FILLER CONTAINING RESIN, AND PRODUCTION METHOD OF DOUBLE-SIDED COPPER CLAD LAMINATE for which I/we have executed an application for Letters Patent of the United States,

(Check One) [] U.S. Serial Number _____ filed _____;
 [X] International Application No. PCT/JP03/04172 filed on April 1, 2003;

and

WHEREAS, Mitsui Mining & Smelting Co., Ltd. (Japanese corporation) of 11-1, Osaki 1-chome, Shinagawa-ku, Tokyo 141-8584, JAPAN
Assignee Citizenship or Corporate Status Address
 ASSIGNEE, is desirous of obtaining the entire right, title and interest in, to and under the said invention and the said application;

NOW, THEREFORE, in consideration of the sum of One Dollar (\$1.00) to me/us in hand paid, and other good and valuable consideration, the receipt of which is hereby acknowledged, I/we, the said ASSIGNOR(S) have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said ASSIGNEE, its successors, legal representatives and assigns, the entire right, title and interest in, to and under the said invention, and the said application and all divisions, renewals and continuations thereof, and all Letters Patent of the United States which may be granted thereon and all reexamination certificates, reissues and extensions thereof, and I/we hereby authorize and request the Commissioner of Patents of the United States, to issue all Letters Patent for said invention to the said ASSIGNEE, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

AND I/WE HEREBY covenant that I/we have the full right to convey the entire interest herein assigned, and that I/we have not executed, and will not execute, any agreement in conflict herewith.

AND I/WE HEREBY further covenant and agree that I/we will communicate to said ASSIGNEE, its successors, legal representatives and assigns, any facts known to me/us respecting said invention, and testify in any legal proceeding, sign all lawful papers, execute all divisional, continuing and reissue applications, make all rightful oaths and generally do everything possible to aid the said ASSIGNEE, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said invention at the expense of the ASSIGNEE.

IN TESTIMONY WHEREOF, I/we hereunto set my/our hands(s) and seal(s) the day and year set opposite my/our signature(s).

<u>Toshifumi Matsushima</u>	<u>Toshifumi MATSUSHIMA</u> L.S.	Date	<u>08/09</u>	<u>2003</u>
<u>Hideaki Miwa</u>	<u>Hideaki MIWA</u> L.S.	Date	<u>08/09</u>	<u>2003</u>
<u>Akira Ichiryu</u>	<u>Akira ICHIRYU</u> L.S.	Date	<u>08/09</u>	<u>2003</u>
<u>Kazuhiro Yamazaki</u>	<u>Kazuhiro YAMAZAKI</u> L.S.	Date	<u>08/09</u>	<u>2003</u>
<u>Tetsuro Sato</u>	<u>Tetsuro SATO</u> L.S.	Date	<u>08/09</u>	<u>2003</u>
<u>Fujio Kuwako</u>	<u>Fujio KUWAKO</u> L.S.	Date	<u>08/09</u>	<u>2003</u>

Witness:

<u>Masaki Uriya</u>	<u>Masaki URIYA</u>	Date	<u>08/09/2003</u>
<small>Name</small>	<small>Name</small>	<small>Date</small>	

Foreign Inventor Sole/Joint Assignment

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